

LINQSOL™ EMC-G208

Black epoxy molding compound



- Green molding compound
- Designed for micro SD cards and other thin, high-density packages
- Designed to satisfy JEDEC MSL-3 reliability

LINQSOL™ EMC-G208 is a halogen-free epoxy molding compound engineered for micro SD cards and other thin, high-density packages. Its high-filler, low-CTE matrix controls warpage, while a high glass-transition temperature of 185 °C secures thermal stability under aggressive reflow profiles. Excellent flow and low melt viscosity promote void-free transfer molding through long, narrow cavities. The formulation meets UL 94 V-0 flammability for robust safety margins. **EMC-G208** is designed to satisfy JEDEC MSL-3 reliability requirements and strict ionic cleanliness limits.

LINQSOL™ EMC-G208 guarantees strong performance and outstanding long-term reliability in demanding environments. This product is deliberately formulated without the inclusion of substances prohibited by the European Union RoHS and REACH. Overall, **EMC-G208** seamlessly integrates advanced material properties, safety compliance, and superior performance to deliver a reliable solution for semiconductor device encapsulation.

Specifications

Property	Value	Unit
General Properties		
Filler content	84	%
Filler shape	Spherical	–
Filler sieving size	75	µm
Specific gravity	1.94	–
Spiral flow at 175 °C	152	cm
Viscosity at 175 °C	9000	cP
Chemical Properties		
Ion content		
Chloride (Cl ⁻) concentration	<15	ppm
Sodium (Na ⁺) concentration	<10	ppm
Water absorption (PCT 24 h)	0.4	%
pH of extract	5–7	–
Mechanical Properties		
Flexural strength at 25 °C	150	MPa
Flexural modulus at 25 °C	18	GPa
Mold shrinkage	0.24	%
Poisson's ratio at 25 °C	0.3	–

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Electrical Properties

Dielectric constant at 1 MHz	4.4	–
Dissipation factor at 1 MHz	0.01	–
Thermal Properties		
Glass transition temperature	185	°C
Coefficient of thermal expansion, α_1	11	ppm/°C
Coefficient of thermal expansion, α_2	45	ppm/°C
Gel time at 175 °C	27	s
Thermal conductivity	0.8	W/mK
Flammability rating	V-0	UL-94

Recommended mold parameters

Parameter	Value	Unit
Molding temperature	170–180	°C
Transfer pressure	40–70	kg _f /cm ²
Transfer time	10–20	s
Cure time at 175 °C	120–150	s
Post mold cure time at 175 °C	6–8	h

The curing conditions provided are recommended guidelines based on typical laboratory results. Actual curing parameters should be defined and validated by the user to ensure compatibility with specific materials, part geometries, and end-use requirements. It is the user's responsibility to optimize and confirm curing conditions that meet their performance and quality standards.

Processing Instructions

- Before use, let **LINQSOL EMC-G208** reach room temperature (23±5 °C) for 24 hours. Keep the bag unopened and stored in a dry location with a relative humidity of ≤50% during thawing to prevent moisture contamination.
- Use the materials within 72 hours after removing the container from cold storage.

Storage and Handling

LINQSOL EMC-G208 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life when stored below 5 °C is 183 days.

The technical information presented in this document is provided for reference only and does not constitute a guarantee of specific properties or performance. Actual results may vary depending on individual conditions and application methods. Users are strongly advised to perform their own testing and validation to determine suitability for their intended use and compliance with relevant regulations.

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